



DUPONT™ LL502

CO-FIRED GOLD VIA FILL

PRODUCT DESCRIPTION

DuPont™ LL502 is a gold via fill compatible with the DuPont™ GreenTape™ 9K7 low temperature co-fired ceramic (LTCC) tape material and the gold system's companion co-fired conductor members: DuPont™ LL505 (internal signal lines), DuPont™ LL507 (external signal lines) and DuPont™ LL509 (cofirable external solderable). DuPont™ LL502 is cadmium and lead free*.

PRODUCT BENEFITS

When used as the via fill in the GreenTape™ 9K7 LTCC system, DuPont LL502 offers the following benefits:

- High reliability, high conductivity metallization
- Co-fire processing
- High circuit density
- Cadmium and lead free*

*Cadmium and lead "free" as used herein means that cadmium and lead are not an intentional ingredients in and are not intentionally added to the referenced product. Trace amounts however may be present.

PROCESSING

For detailed recommendations on the use of the DuPont™ LL502 via fill with the GreenTape™ 9K7 system, consult this data sheet and the DuPont™ GreenTape™ LTCC Design Guide. For compatible co-fired and post fired conductor compositions, consult the DuPont™ GreenTape™ 9K7 Product Selector Guide.

Printing

The composition should be thoroughly stirred prior to use. This is best achieved by a slow, gentle mixing by hand for 1 to 2 minutes using a clean, burr-free spatula (flexible plastic or stainless steel). Care must be taken to avoid air entrapment.

Prior to the via fill step, via openings are formed/punched in the preconditioned GreenTape™ 9K7 green sheets per the applicable circuit design for the respective layers of the build.

Table 1-Typical Properties

Property	Value
Viscosity, (Pa.s, 1 rpm, 25°C) ¹	6500-8500
Solids, (%) ²	91.0-93.0
Clean-up solvent	1-Propoxy-2-Proponal
Thinner	9450

¹ Brookfield HBT, SC4-14 / 6R spindle and utility cup

² 750°C

Print DuPont™ LL502 directly into the open vias using typical through-hole screen printing methods and a stencil mask. The use of a vacuum stone or other support structure which uniformly distributes a vacuum across the green sheet is recommended to assist with the uniform and complete filling of the via array patterns, as well as secure the green sheet to the printer's stage plate during the printing process.

Printing should be performed in a clean, well-ventilated area. Optimum printing characteristics are generally achieved when the room and paste container temperatures are in the 20 to 23°C range.

Drying

Dry via prints in a well-ventilated oven or conveyor dryer for 5 minutes at 100°C. Do not over-dry. An alternative drying method is to allow the DuPont™ LL502 fills to dry 6 to 8 hours at ambient room temperature.

Lamination

Collate, stack and laminate multiple sheets of the printed circuit patterns according to the recommended processing parameters detailed in the DuPont™ GreenTape™ LTCC Design Guide.

Typical lamination parameters are 3000 psi at 70°C for 10 minutes. Lamination pressures may vary slightly based upon part design and the individual tape lot shrinkage factors.



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Firing

Fire in a well-ventilated conveyor or static furnace. Air flows and extraction rates should be optimized to ensure that oxidizing conditions exist within the muffle and that no exhaust gases enter the room.

GreenTape™ 9K7 requires the use of dedicated, specially coated setters in order to prevent parts from sticking during firing.

Consult the DuPont™ GreenTape™ 9K7 low temperature co-fired ceramic (LTCC) system data sheets and DuPont™ GreenTape™ LTCC Design Guide for additional details.

For further information regarding firing profiles, furnace recommendations and setter tile choices, please contact your local DuPont™ Technical Service Representative.

STORAGE AND SHELF LIFE

Containers should be stored, tightly sealed, in a clean, stable environment at room temperature (<25°C). Shelf life of material in unopened containers is six months from date of shipment. Some settling of solids may occur and compositions should be thoroughly mixed prior to use.

SAFETY AND HANDLING

For Safety and Handling information pertaining to this product, read the Material Safety Data Sheet (MSDS).

FOR MORE INFORMATION ON DUPONT™ LL502 OR OTHER DUPONT MICROCIRCUIT MATERIALS, PLEASE CONTACT YOUR LOCAL REPRESENTATIVE:

Americas

DuPont Microcircuit Materials
14 TW Alexander Drive
Research Triangle Park, NC 27709
USA
Tel +1 800 284 3382 (calls within USA)
Tel +1 919 248 5188 (calls outside USA)

Europe, Middle East & Africa

Du Pont (UK) Ltd
Coldharbour Lane
Bristol BS16 1QD
UK
Tel +44 117 931 3191

Asia

Du Pont Kubushiki Kaisha
MCM Technical Lab
DuPont Electronics Center
KSP R&D B213, 2-1,
Sakado 3-chome, Takatsu-ku,
Kawasaki-shi, Kanagawa, 213-0012
Japan
Tel +81 44 820 7575

DuPont Taiwan Ltd
45, Hsing-Pont Road
Taoyuan, 330
Taiwan
Tel +886 3 377 3616

DuPont China Holding Company Ltd
Bldg. 11, 399 Keyuan Road
Zhangjiang Hi-Tech Park
Pudong New District
Shanghai 201203
Tel +86 21 3862 2888

DuPont Korea Inc.
3-5th Floor, Asia tower #726
Yeoksam-dong, Gangnam-gu
Seoul 135-719, Korea
Tel +82 2 2222 5275

E.I. DuPont India Private Limited
7th Floor, Tower C, DLF Cyber Greens
Sector-25A, DLF City, Phase-III
Gurgaon 122 002 Haryana, India
Tel +91 124 409 1818

Du Pont Company (Singapore) Pte Ltd
1 HarbourFront Place, #11-01
HarbourFront Tower One
Singapore 098633
Tel +65 6586 3022

mcm.dupont.com

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CAUTION: Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see "DuPont Medical Caution Statement," H-50102-5 K-28898 (4/15)